

5 ABSTRACT

10 A semiconductor package which is improved in thinness and heat radiation and a
method for making the same. The package includes a semiconductor chip electrically
connected to leads of a leadframe via input and output bond pads. The leadframe may
15 have a ground ring formed therein. The leads and semiconductor chip are at least
partially encapsulated by an encapsulant. The semiconductor chip and leads have bottom
surfaces which are externally exposed to improve heat radiation and reduce the thickness
of the package. The package is made by placing the leadframe having leads onto
adhesive tape, affixing a semiconductor chip into an open space on the leadframe,
15 pressurizing the leadframe and chip downwardly for securement to the adhesive tape,
electrically connecting input bond pads and output bond pads on the chip to the leads; at
least partially encapsulating the leads and semiconductor chip; removing the tape from
the bottom surfaces of the leads and chip; and cutting the leadframe to form the package.
In an alternate embodiment, a chip paddle is connected to the leadframe and the
20 semiconductor chip is secured to the chip paddle via an adhesive.